

## **Technical Data Sheet**

### MODEL NO: S5730ANW4P-H-5000k

0.5w 5.7 x 3.0mm Pure White SMD

### Features

●Package: 2500pcs per reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

### Applications:

Indicators

•Automotive : backlighting in dashboard and switch

Dice material	Emitted color	Lens Color
InGaN	Pure White	Yellow diffused

## ${\tt Electrical/Optical \ Characteristics(Ta=25^{\circ}C)}$

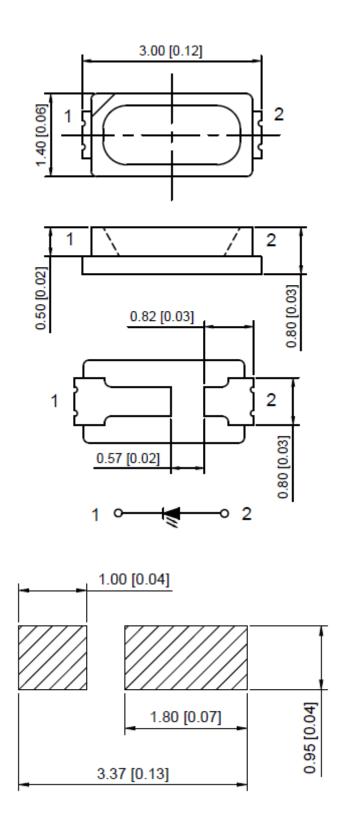
Parameter	Test	Symbol	Value			l la it
	Condition		Min	Тур	Max	Unit
Luminous Flux	IF=150mA	arphi (lm)	53		58	lm
Chromaticity Coordinates	IF=150mA	Х		0.346		-
		Y		0.359		-
Color Temperature	IF=150mA	ССТ	4750	5000	5300	К
Color Rendering Index	IF=150mA	Ra	70			-
Forward voltage	IF=150mA	VF	2.8		3.8	V
Viewing angle	IF=150mA	2 <i> </i>		120		Deg
Reverse current	Vr=5V	lr			10	μA

### Absolute Maximum Ratings(Ta=25°C)

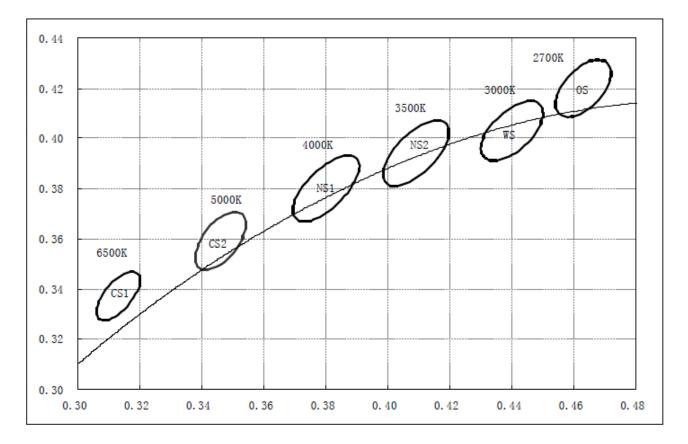
Parameter	Symbol	Value	Unit
Power dissipation	Pd	120	mW
Forward current	lf	40	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+85	°C
Storage temperature range	Tstg	-40 ~+100	°C
Peak pulsing current (1/10 duty f=1kHz)	IFP	100	mA



PACKAGING DIMENSIONS (mm):





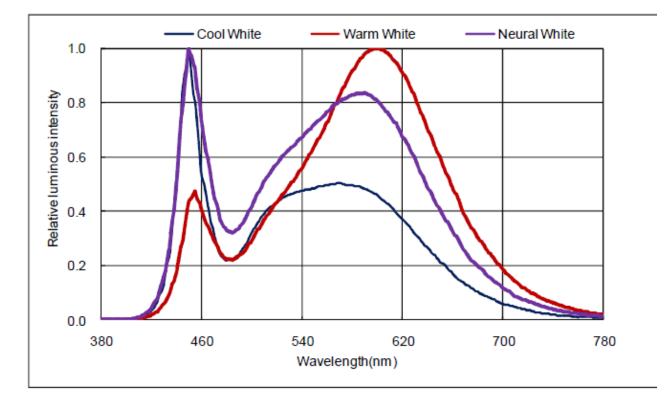


## Bin Range of Chromaticity

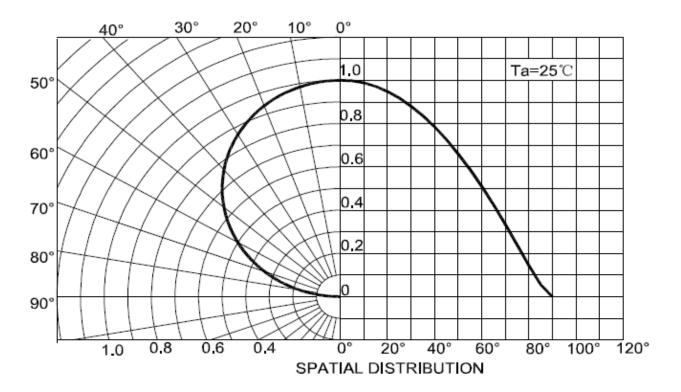
CCT 色温	Bin Code Bin代码	CIE_x	CIE_y
6500K	CS1 6000-7000K	0.313	0.337
5000K	CS2 4750-5300K	0.346	0.359
4000K	NS1 3800-4250K	0.380	0.380
3400K	NS2 3200-3600K	0.409	0.394
3000K	WS 2800-3100K	0.440	0.403
2700K	OS 2600-2800K	0.463	0.420



Relative spectral emission



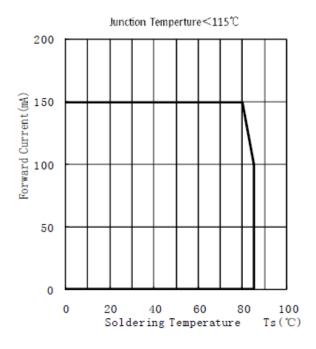
Radiation diagram

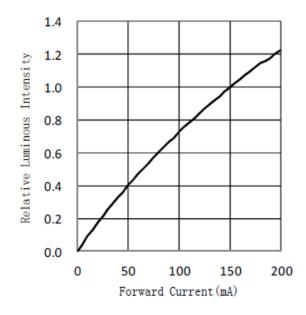




### Soldering Temperature vs. Forward Current

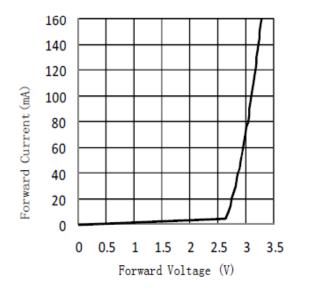
Forward Current VS. Relative Intensity

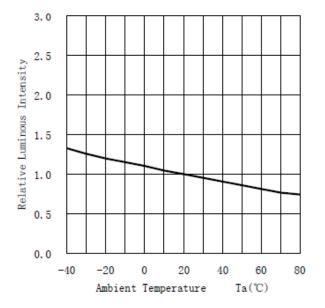




Forward Voltage VS. Forward Current

Ambient Temperature VS. Relative Intensity







### **Precautions For Use :**

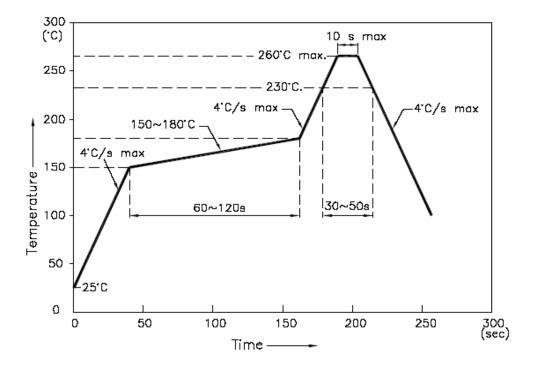
### **Over - current - proof**

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

### Storage

1. The operation of temperature and R.H. are :  $5^{\circ}$ C ~  $30^{\circ}$ C ,  $60^{\circ}_{0}$ R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}C\pm5^{\circ}C$  for 15 hrs.
- Reflow Temp/Time



### NOTES:

- 1. We recommend the reflow temperature  $245 \,^{\circ}C(\pm 5 \,^{\circ}C)$ .the maximum soldering temperature should be limited to  $260 \,^{\circ}C$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

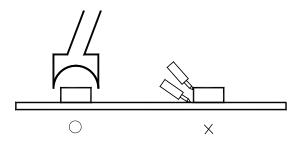


### ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

### Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 

solder etc.